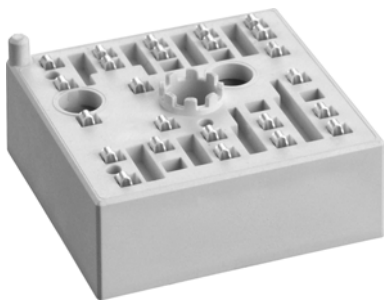


SKiiP 11AC12T4V1



MiniSKiiP® 1

SKiiP 11AC12T4V1

Features

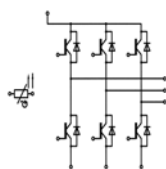
- Trench 4 IGBT's
- Robust and soft freewheeling diodes in CAL technology
- Highly reliable spring contacts for electrical connections
- UL recognised file no. E63532

Typical Applications*

- Inverter up to 8 kVA
- Typical motor power 4 kW

Remarks

- V_{CEsat} , V_F = chip level value
- Case temp. limited to $T_C = 125^\circ\text{C}$ max. (for baseplateless modules $T_C = T_S$)
- product rel. results valid for $T_j \leq 150$ (recomm. $T_{op} = -40 \dots +150^\circ\text{C}$)



AC

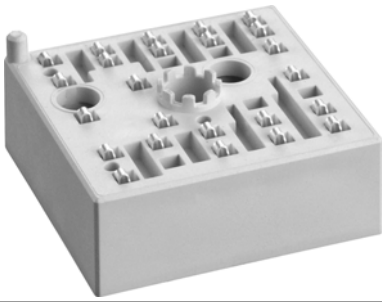
Absolute Maximum Ratings

Symbol	Conditions	Values	Unit
Inverter - IGBT			
V_{CES}	$T_j = 25^\circ\text{C}$	1200	V
I_C	$T_j = 175^\circ\text{C}$	$T_s = 25^\circ\text{C}$	12
		$T_s = 70^\circ\text{C}$	12
I_{Cnom}		8	A
I_{CRM}	$I_{CRM} = 3 \times I_{Cnom}$	24	A
V_{GES}		-20 ... 20	V
t_{psc}	$V_{CC} = 800\text{ V}$	$T_j = 150^\circ\text{C}$	10
	$V_{GE} \leq 15\text{ V}$		
	$V_{CES} \leq 1200\text{ V}$		
T_j		-40 ... 175	$^\circ\text{C}$
Inverse - Diode			
I_F	$T_j = 175^\circ\text{C}$	$T_s = 25^\circ\text{C}$	15
		$T_s = 70^\circ\text{C}$	12
I_{Fnom}		8	A
I_{FRM}	$I_{FRM} = 3 \times I_{Fnom}$	24	A
I_{FSM}	10 ms, sin 180°, $T_j = 150^\circ\text{C}$	36	A
T_j		-40 ... 175	$^\circ\text{C}$
Module			
$I_{t(RMS)}$	$T_{terminal} = 80^\circ\text{C}$, 20A per spring	20	A
T_{stg}		-40 ... 125	$^\circ\text{C}$
V_{isol}	AC sinus 50Hz, t = 1 min	2500	V

Characteristics

Symbol	Conditions	min.	typ.	max.	Unit
Inverter - IGBT					
$V_{CE(sat)}$	$I_C = 8\text{ A}$ $V_{GE} = 15\text{ V}$ chipelevel	$T_j = 25^\circ\text{C}$	1.85	2.10	V
		$T_j = 150^\circ\text{C}$	2.25	2.45	V
V_{CE0}		$T_j = 25^\circ\text{C}$	0.8	0.9	V
		$T_j = 150^\circ\text{C}$	0.7	0.8	V
r_{CE}	$V_{GE} = 15\text{ V}$	$T_j = 25^\circ\text{C}$	131	150	m Ω
		$T_j = 150^\circ\text{C}$	194	206	m Ω
$V_{GE(th)}$	$V_{GE} = V_{CE}$, $I_C = 1\text{ mA}$	5	5.8	6.5	V
I_{CES}	$V_{GE} = 0\text{ V}$ $V_{CE} = 1200\text{ V}$	$T_j = 25^\circ\text{C}$	0.1	0.3	mA
					mA
C_{ies}	$V_{CE} = 25\text{ V}$		0.49		nF
C_{oes}	$V_{GE} = 0\text{ V}$		0.05		nF
C_{res}			0.03		nF
Q_G	- 8 V...+ 15 V		45		nC
R_{Gint}	$T_j = 25^\circ\text{C}$		0.00		Ω
$t_{d(on)}$	$V_{CC} = 600\text{ V}$	$T_j = 150^\circ\text{C}$	32		ns
t_r	$I_C = 8\text{ A}$	$T_j = 150^\circ\text{C}$	28		ns
E_{on}	$R_{Gon} = 56\ \Omega$ $R_{Goff} = 56\ \Omega$	$T_j = 150^\circ\text{C}$	0.87		mJ
$t_{d(off)}$	$di/dt_{on} = 280\text{ A}/\mu\text{s}$	$T_j = 150^\circ\text{C}$	300		ns
t_f	$di/dt_{off} = 90\text{ A}/\mu\text{s}$	$T_j = 150^\circ\text{C}$	65		ns
E_{off}	$V_{GE} = +15/-15\text{ V}$	$T_j = 150^\circ\text{C}$	0.75		mJ
$R_{th(j-s)}$	per IGBT		1.84		K/W

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Features

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- UL recognised file no. E63532

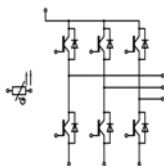
Typical Applications*

- Inverter up to 8 kVA
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Remarks

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- product rel. results valid for $T_j \leq 150$ (recomm. $T_{op} = -40 \dots +150^\circ\text{C}$)

Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
Inverse - Diode						
$V_F = V_{EC}$	$I_F = 8 \text{ A}$ $V_{GE} = 0 \text{ V}$ chiplevel	$T_j = 25^\circ\text{C}$		2.3	2.6	V
		$T_j = 150^\circ\text{C}$		2.4	2.7	V
V_{F0}		$T_j = 25^\circ\text{C}$		1.3	1.5	V
		$T_j = 150^\circ\text{C}$		0.9	1.1	V
r_F		$T_j = 25^\circ\text{C}$		129	144	m Ω
		$T_j = 150^\circ\text{C}$		181	198	m Ω
I_{RRM}	$I_F = 8 \text{ A}$	$T_j = 150^\circ\text{C}$		7.7		A
Q_{rr}	$di/dt_{off} = 350 \text{ A}/\mu\text{s}$	$T_j = 150^\circ\text{C}$		1.3		μC
E_{rr}	$V_{GE} = -15 \text{ V}$ $V_{CC} = 600 \text{ V}$	$T_j = 150^\circ\text{C}$		0.53		mJ
$R_{th(j-s)}$	per Diode			2.53		K/W
Module						
M_s	to heat sink		2		2.5	Nm
w				35		g
Temperatur Sensor						
R_{100}	$T_C = 100^\circ\text{C}$ ($R_{25} = 1000\Omega$)			1670 \pm 3%		Ω
$R(T)$	$R(T) = 1000\Omega [1 + A(T - 25^\circ\text{C}) + B(T - 25^\circ\text{C})^2]$], $A = 7.635 \cdot 10^{-3} \text{ }^\circ\text{C}^{-1}$, $B = 1.731 \cdot 10^{-5} \text{ }^\circ\text{C}^{-2}$					



AC

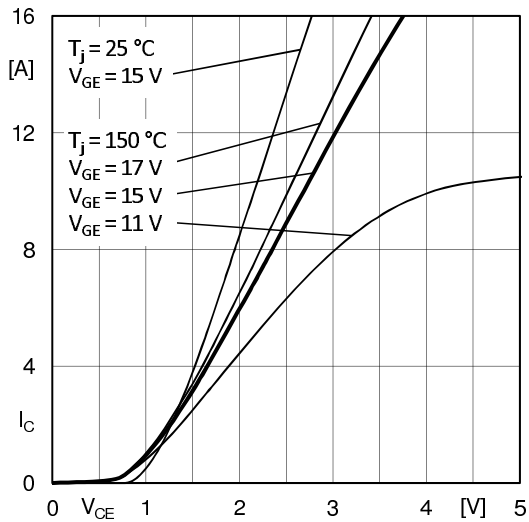


Fig. 1: Typ. output characteristic, inclusive $R_{CC'+EE'}$

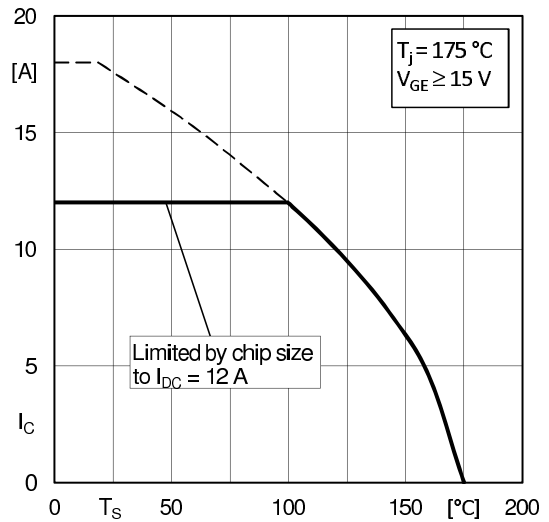


Fig. 2: Rated current vs. temperature $I_C = f(T_S)$

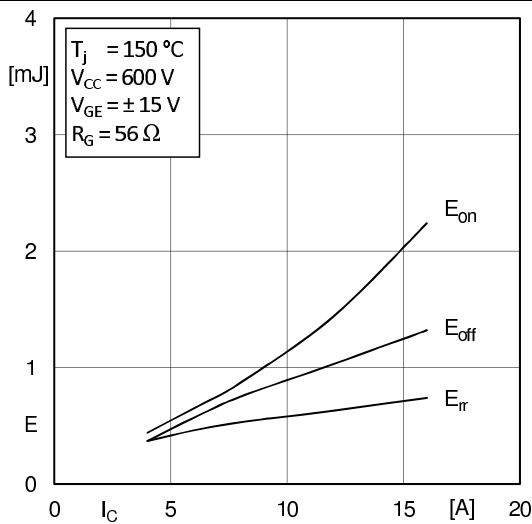


Fig. 3: Typ. turn-on /-off energy = $f(I_C)$

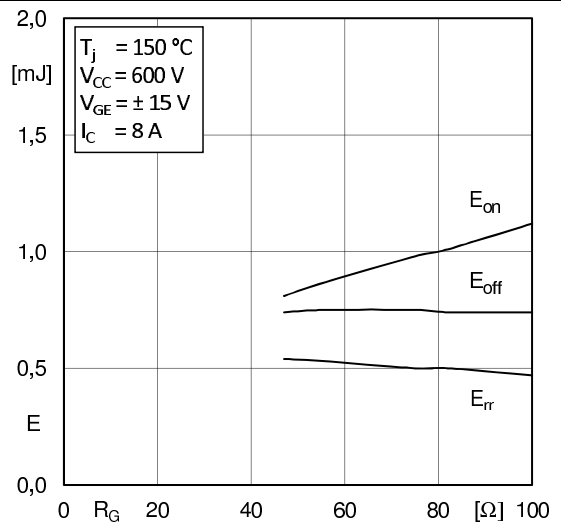


Fig. 4: Typ. turn-on /-off energy = $f(R_G)$

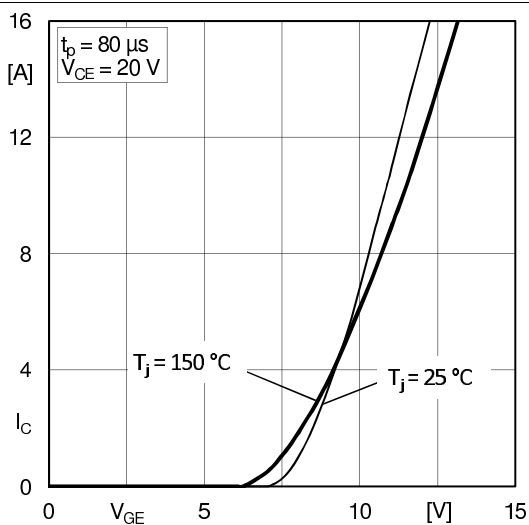


Fig. 5: Typ. transfer characteristic

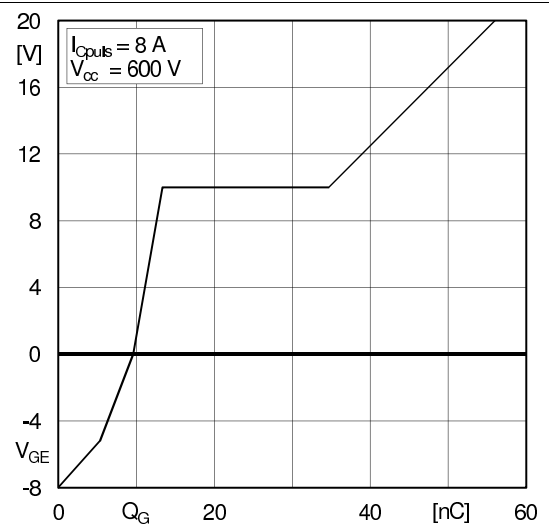
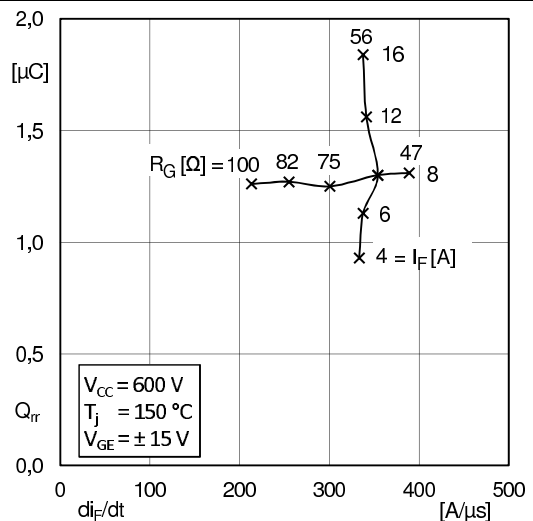
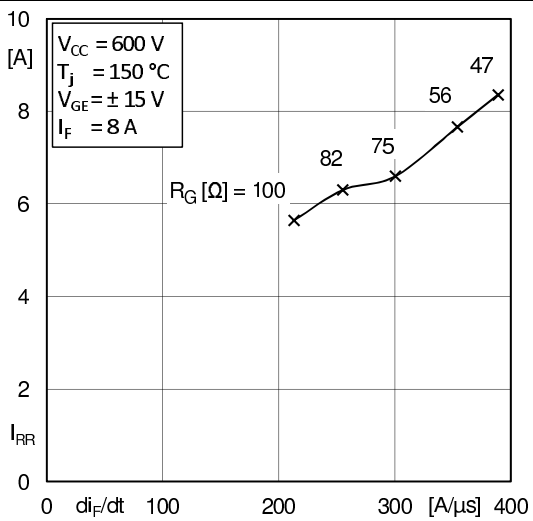
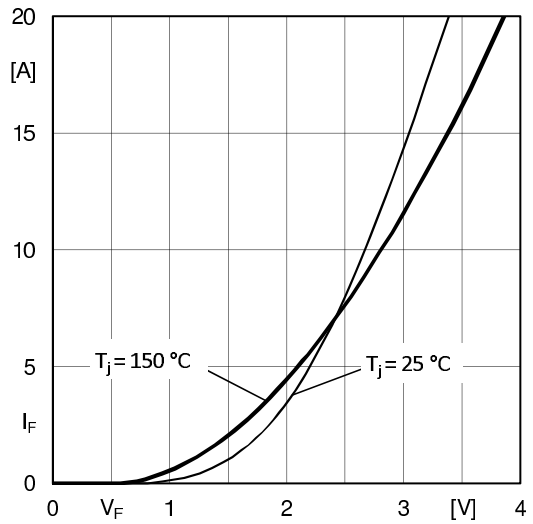
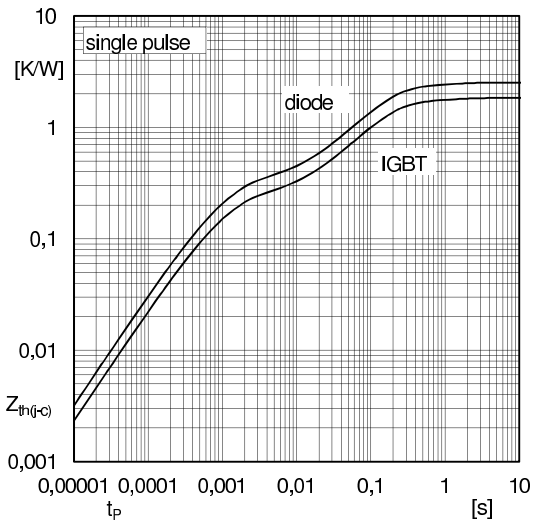
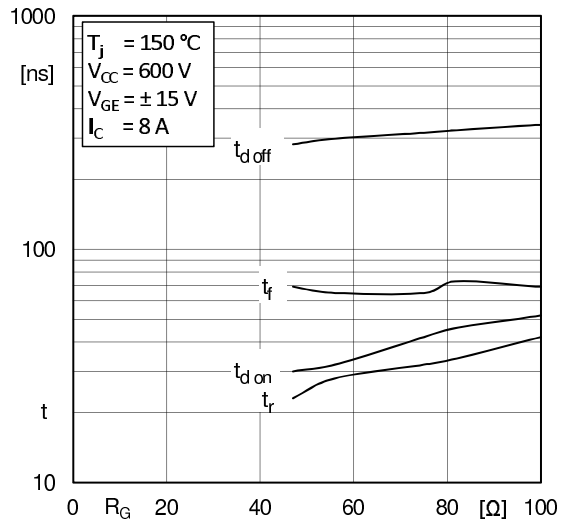
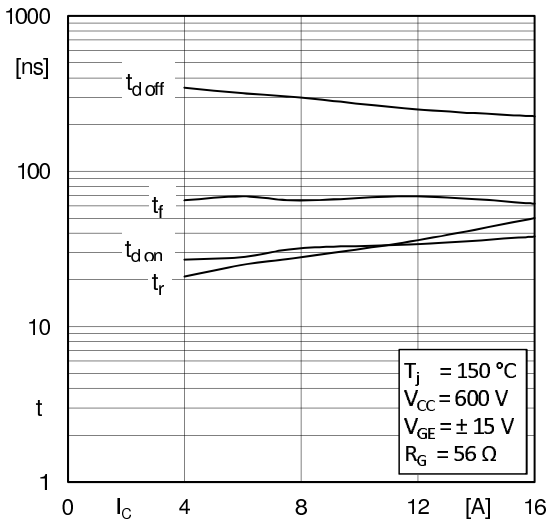
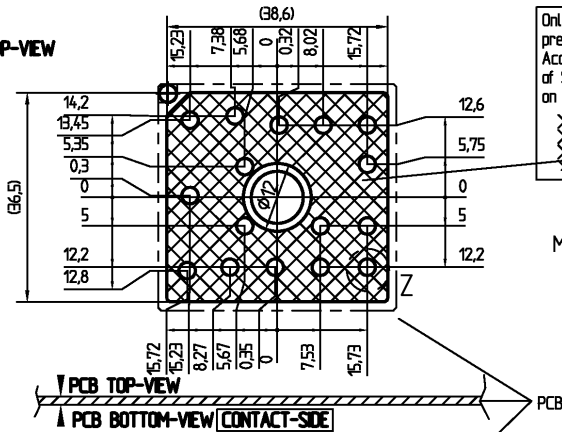


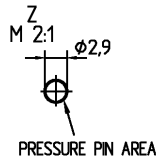
Fig. 6: Typ. gate charge characteristic



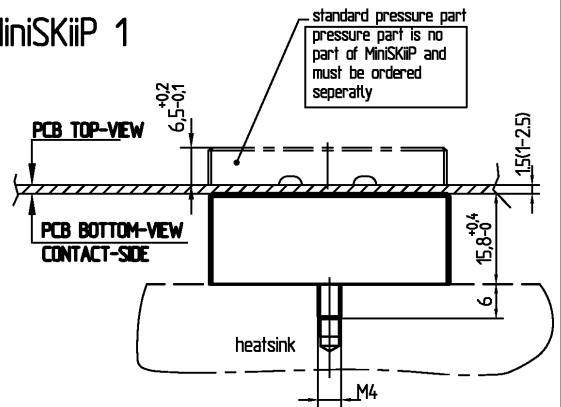
PCB PCB TOP-VIEW



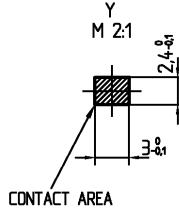
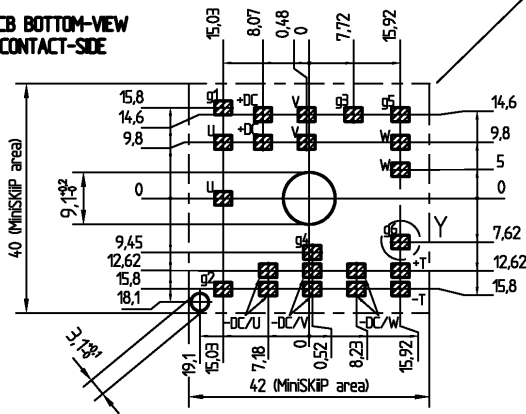
Only for the standard pressure part:
Accessible for mounting of SMD (max height 3.5) on PCB by customer



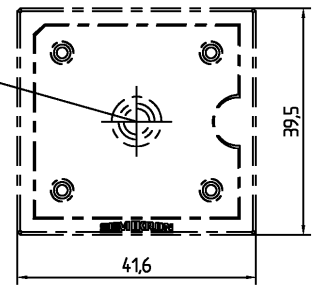
MiniSKiiP 1



PCB BOTTOM-VIEW CONTACT-SIDE

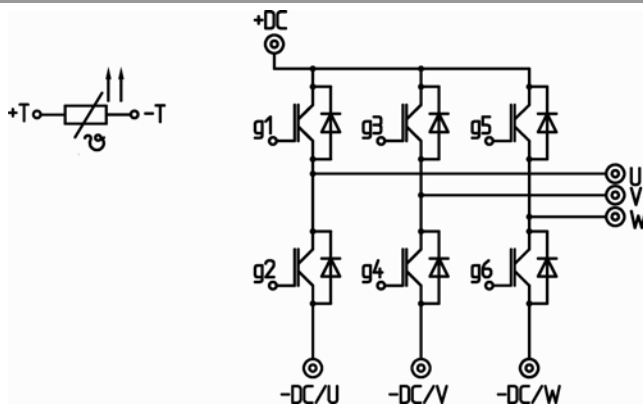


For mounting please follow the assembly instruction



measure: mm
tolerance: ISO 2768-f

pinout, dimensions



- ⊙ power connector
- control connector

pinout

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX

* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our staff.